

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSG0810NDI	**Issued**	04. April 2021
MA#	MA001624626		
Package	PG-TISON-8-4	**Weight***	112.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.846	0.75	0.75	7537	7537
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	zinc	7440-66-6	0.043	0.04		384	
	non noble metal	iron	7439-89-6	0.862	0.77		7679	
	non noble metal	copper	7440-50-8	34.984	31.18	32.00	311800	319959
wire	non noble metal	copper	7440-50-8	0.009	0.01	0.01	85	85
encapsulation	organic material	carbon black	1333-86-4	0.094	0.08		839	
	plastics	epoxy resin	-	4.849	4.32		43213	
	inorganic material	silicondioxide	60676-86-0	42.131	37.55	41.95	375495	419547
leadfinish	non noble metal	tin	7440-31-5	1.180	1.05	1.05	10514	10514
plating	noble metal	silver	7440-22-4	0.087	0.08	0.08	772	772
solder	non noble metal	tin	7440-31-5	0.027	0.02		236	
	noble metal	silver	7440-22-4	0.033	0.03		295	
	non noble metal	lead	7439-92-1	1.266	1.13	1.18	11281	11812
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.008	0.01		69	
	non noble metal	zinc	7440-66-6	0.031	0.03		276	
	non noble metal	iron	7439-89-6	0.619	0.55		5515	
	non noble metal	copper	7440-50-8	25.123	22.39	22.98	223914	229774
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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